

MOUNTING ELECTRONIC COMPONENTS

Abstract of the Disclosure

A method of mounting an electronic component having at least one contact extending across a part of its undersurface may include providing a support
5 smaller in area than the undersurface of the component and having a contact pad for connection to the contact. The contact pad may have a first portion extending across an upper surface of the support adjacent one edge and a second portion extending from the edge
10 across a side surface of the support. The method may also include positioning the electronic component and the support with the undersurface of the component adjacent the upper surface of the support. This is done so that the first portion of the contact pad is
15 aligned with and spaced apart from a first portion of the contact, and the second portion of the contact pad is aligned with and disposed inwardly of a second portion of the contact.